

STS4DNF60L

N-channel 60 V, 0.045 Ω, 4 A, SO-8 STripFET™ Power MOSFET

Features

Туре	V _{DSS}	R _{DS(on)}	I _D
STS4DNF60L	60V	<0.055Ω	4A

- Standard outline for easy automated surface mount assembly
- Low threshold drive

Application

Switching applications

Description

This Power MOSFET is the latest development of STMicroelectronics unique "single feature size" strip-based process. The resulting transistor shows extremely high packing density for low onresistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

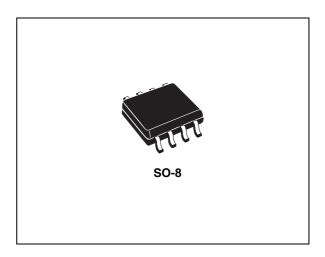


Figure 1. Internal schematic diagram

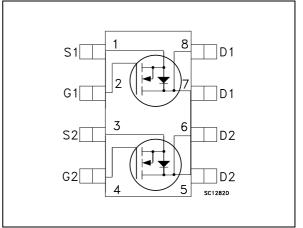


Table 1.Device summary

Order code	Marking	Package	Packaging
STS4DNF60L	4DF60L	SO-8	Tape & reel

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1 Electrical ratings

Table 2.	Absolute	maximum	ratings
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Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage ($V_{GS} = 0$)	60	V
V_{GS}	Gate- source voltage	± 15	V
Ι _D	Drain current (continuous) at $T_C = 25 \ ^{\circ}C$	4	А
Ι _D	Drain current (continuous) at T _C = 100 °C	2.5	А
I _{DM} ⁽¹⁾	Drain current (pulsed)	16	А
P _{TOT} ⁽²⁾	Total dissipation at T_{C} = 25 °C	2	W
$E_{AS}^{(3)}$	Single pulse avalanche energy	80	mJ
T _j T _{stg}	Operating junction temperature Storage temperature	- 55 to 150	°C

1. Pulse width limited by safe operating area

2. P_{TOT}=1.6 W for single operation

3. Starting T_J = 25 °C, I_D = 4 A, V_{DD} = 30 V

Table 3. Thermal data

Symbol	Parameter	Value	Unit
Rthj-pcb	Thermal resistance junction-pcb D.O. ⁽¹⁾	62.5	°C/W

1. When mounted on inch² FR-4 board, 2 Oz Cu, t \leq 10sec, dual operation



2 Electrical characteristics

(T_C = 25 °C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	$I_D = 250 \ \mu A, \ V_{GS} = 0$	60			V
I _{DSS}	Zero gate voltage drain current (V _{GS} = 0)	V _{DS} = Max rating V _{DS} = Max rating, T _C =125 °C			1 10	μΑ μΑ
I _{GSS}	Gate-body leakage current (V _{DS} = 0)	V _{GS} = ± 15 V			± 100	nA
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	1	1.7	2.5	V
R _{DS(on)}	Static drain-source on resistance	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 2 \text{ A}$ $V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 2 \text{ A}$		0.045 0.050	0.055 0.065	Ω Ω

Table 4. On /off states

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
9 _{fs}	Forward transconductance	V _{DS} =25 V, I _D =2 A	-	25	-	S
C _{iss} C _{oss} C _{rss}	Input capacitance Output capacitance Reverse transfer capacitance	V _{DS} = 25 V, f = 1 MHz, V _{GS} = 0	-	1030 140 40	-	pF pF pF
Q _g Q _{gs} Q _{gd}	Total gate charge Gate-source charge Gate-drain charge	$V_{DD} = 48 V, I_D = 4 A,$ $V_{GS} = 4.5 V$ (see <i>Figure 13</i>)	-	15 4 4	-	nC nC nC



	o mitoring timeo					
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r	Turn-on delay time Rise time	$V_{DD} = 30 \text{ V}, \text{ I}_{D} = 2.2 \text{ A},$ $R_{G} = 4.7 \Omega, V_{GS} = 10 \text{ V}$	-	15 28	-	ns ns
t _{d(off)} t _f	Turn-off delay time Fall time	(see <i>Figure 12</i>)	-	45 10	-	ns ns

Table 6. Switching times

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{SD} I _{SDM} ⁽¹⁾	Source-drain current Source-drain current (pulsed)		-		4 16	A A
V _{SD} ⁽²⁾	Forward on voltage	I _{SD} = 4 A, V _{GS} = 0	-		1.2	V
t _{rr} Q _{rr} I _{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD} = 4 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$ $V_{DD} = 20 \text{ V}$ (see <i>Figure 17</i>)	-	85 85 2		ns nC A

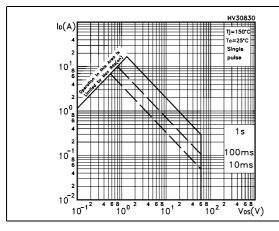
1. Pulse width limited by safe operating area

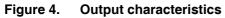
2. Pulsed: Pulse duration = 300 μ s, duty cycle 1.5%



2.1 Electrical characteristics (curves)

Figure 2. Safe operating area





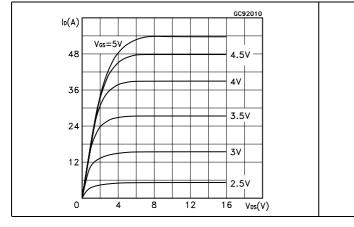
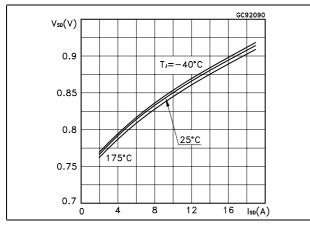
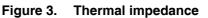
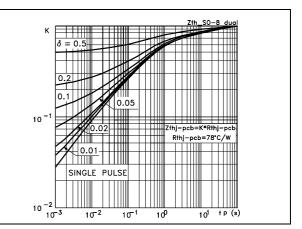
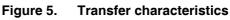


Figure 6. Source-drain diode forward characteristics









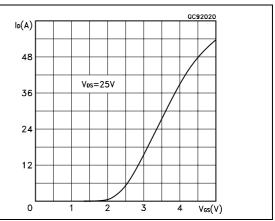
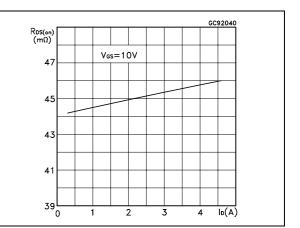


Figure 7. Static drain-source on resistance





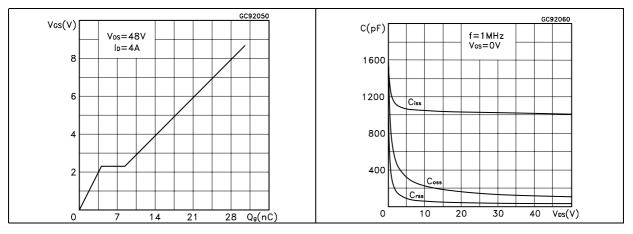
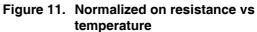
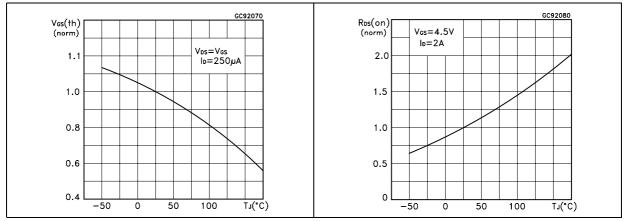


Figure 8. Gate charge vs gate-source voltage Figure 9. Capacitance variations

Figure 10. Normalized gate threshold voltage vs temperature







3 **Test circuits**

Figure 12. Switching times test circuit for resistive load

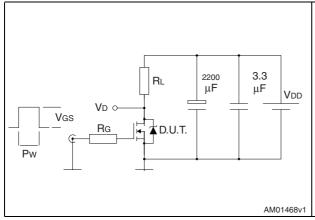
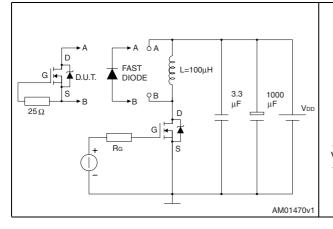
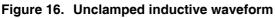


Figure 14. Test circuit for inductive load switching and diode recovery times





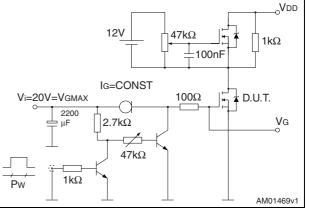
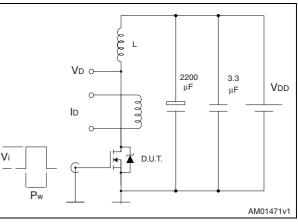


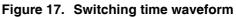
Figure 13. Gate charge test circuit

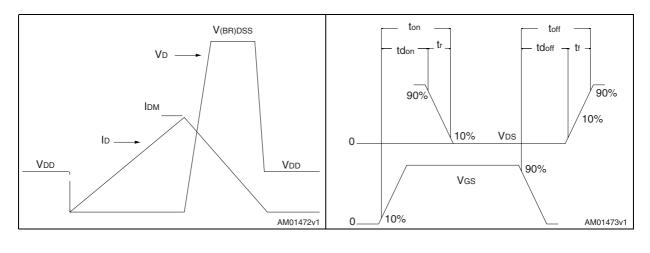
Figure 15. Unclamped Inductive load test











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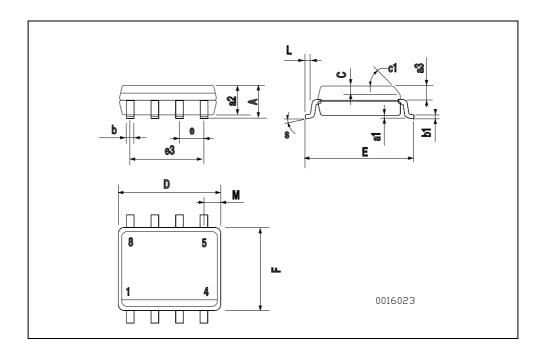
4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.



DIM.		mm.			inch			
DIWI.	MIN.	ТҮР	MAX.	MIN.	TYP.	MAX.		
А			1.75			0.068		
a1	0.1		0.25	0.003		0.009		
a2			1.65			0.064		
a3	0.65		0.85	0.025		0.033		
b	0.35		0.48	0.013		0.018		
b1	0.19		0.25	0.007		0.010		
С	0.25		0.5	0.010		0.019		
c1		•	45	(typ.)	•	•		
D	4.8		5.0	0.188		0.196		
E	5.8		6.2	0.228		0.244		
е		1.27			0.050			
e3		3.81			0.150			
F	3.8		4.0	0.14		0.157		
L	0.4		1.27	0.015		0.050		
М			0.6	1		0.023		

SO-8 MECHANICAL DATA



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5 Revision history

Table 8.Document revision history

Date	Revision	Changes
30-May-2005	5	Initial electronic version
29-Mar-2006	6	Modified <i>Figure 2</i> and <i>Figure 3</i>
16-May-2006	7	Modified internal schematic diagram
29-Aug-2007	8	Marking has been updated
30-Mar-2010	9	Inserted E _{AS} value in <i>Table 2: Absolute maximum ratings</i>



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